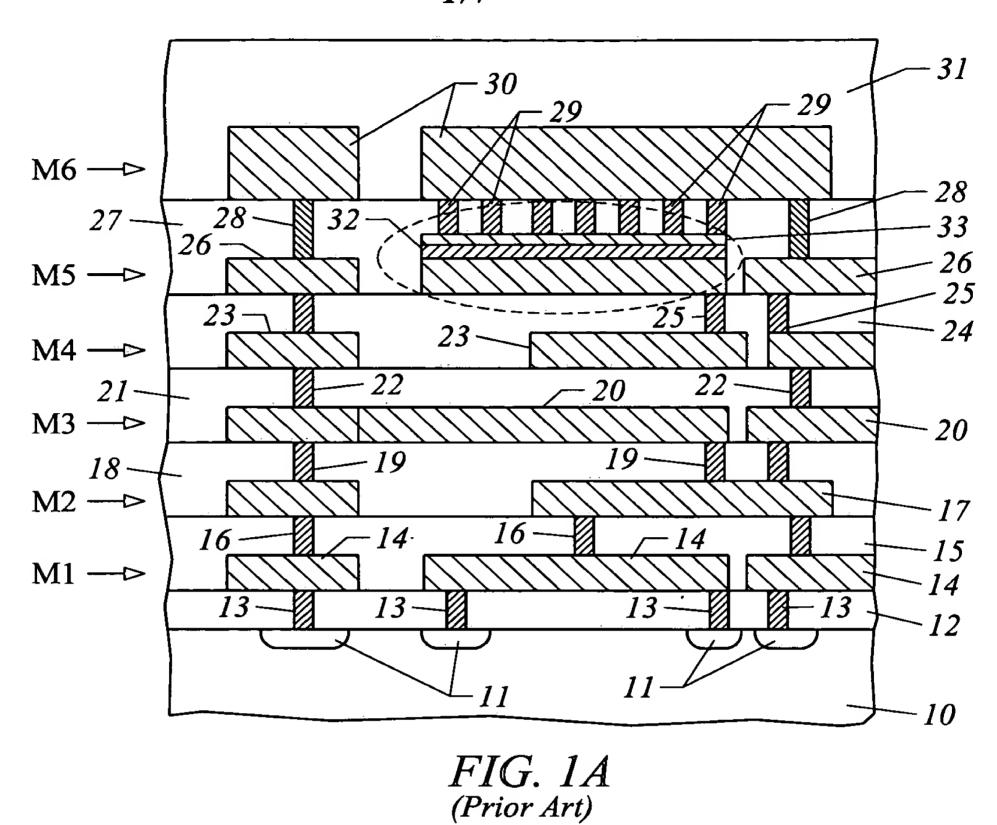
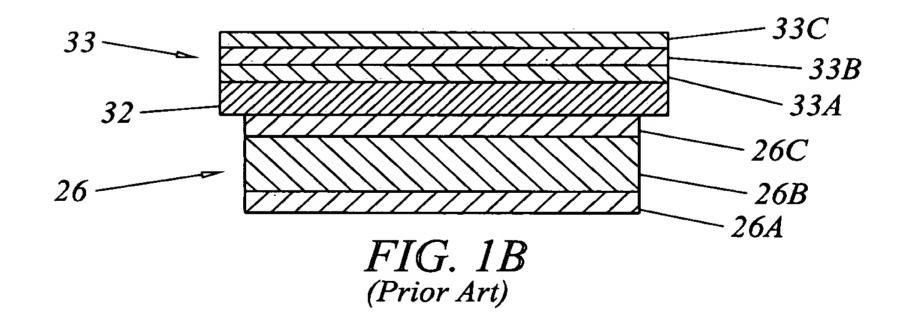
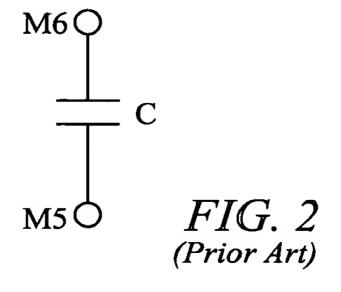
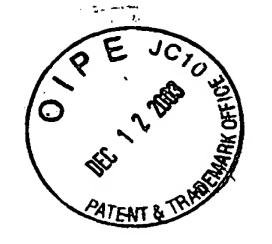


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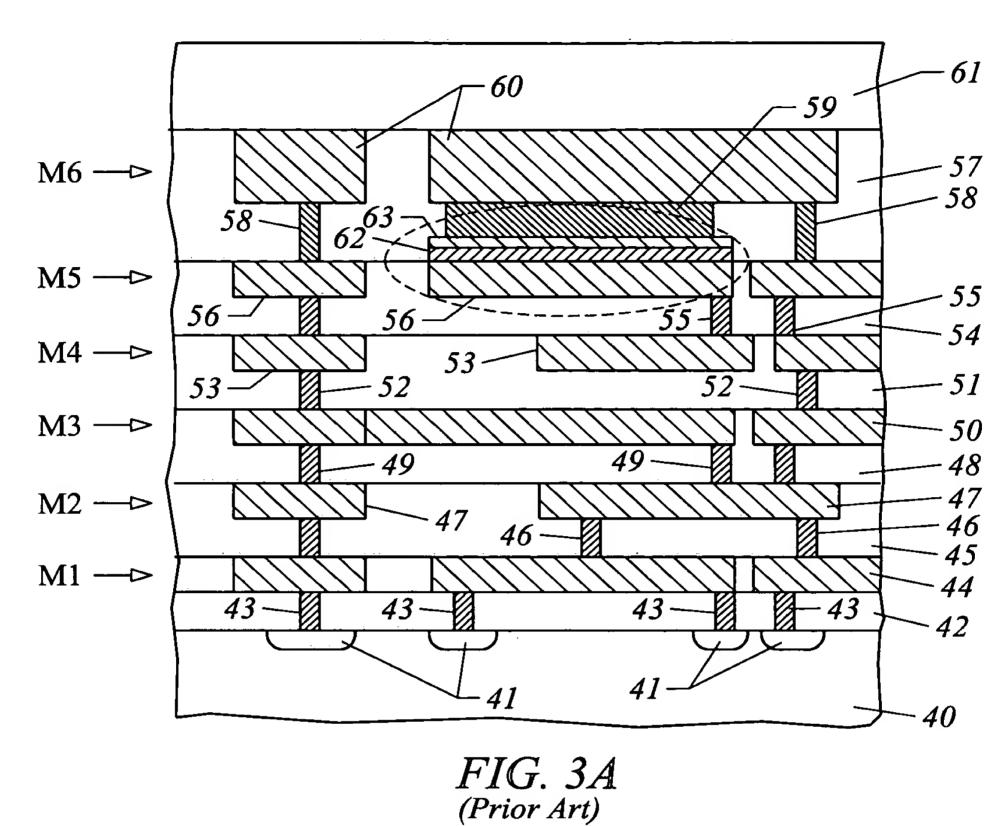


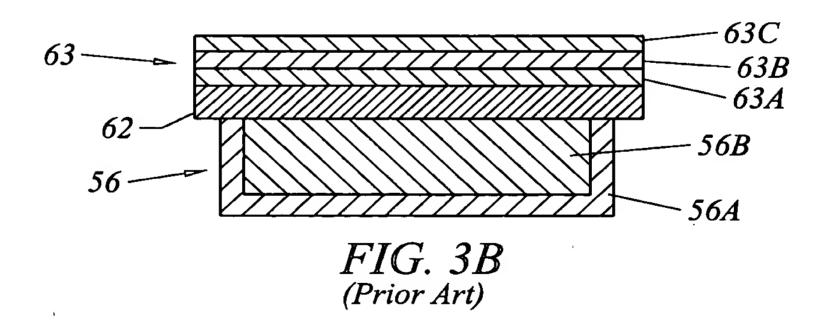


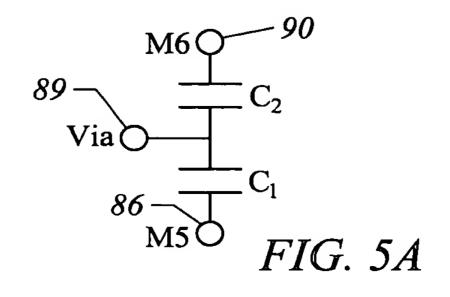


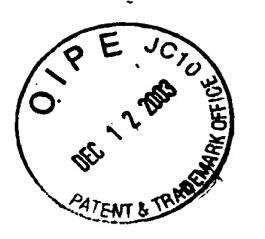


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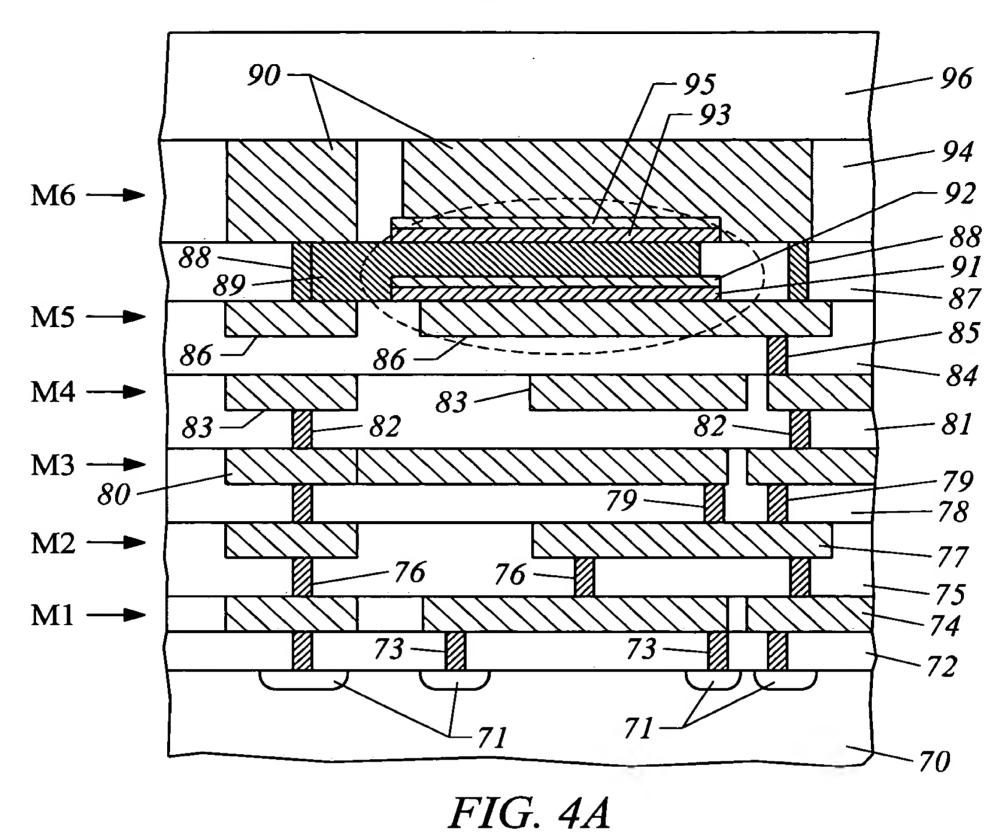


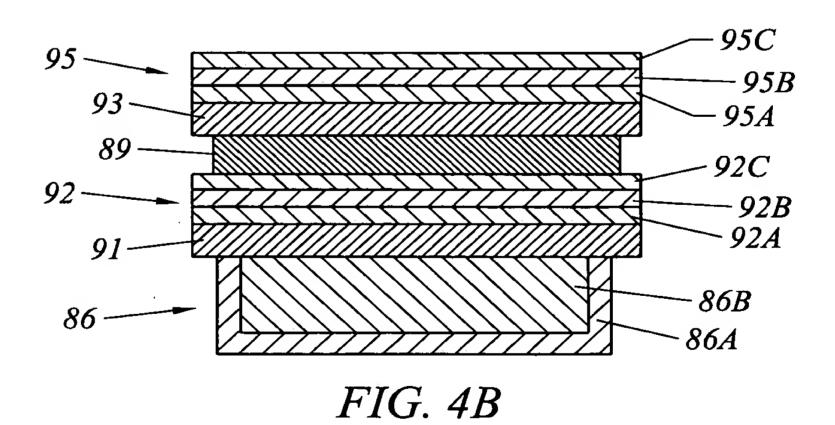






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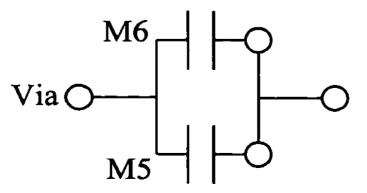
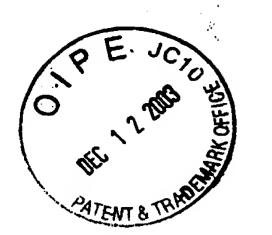
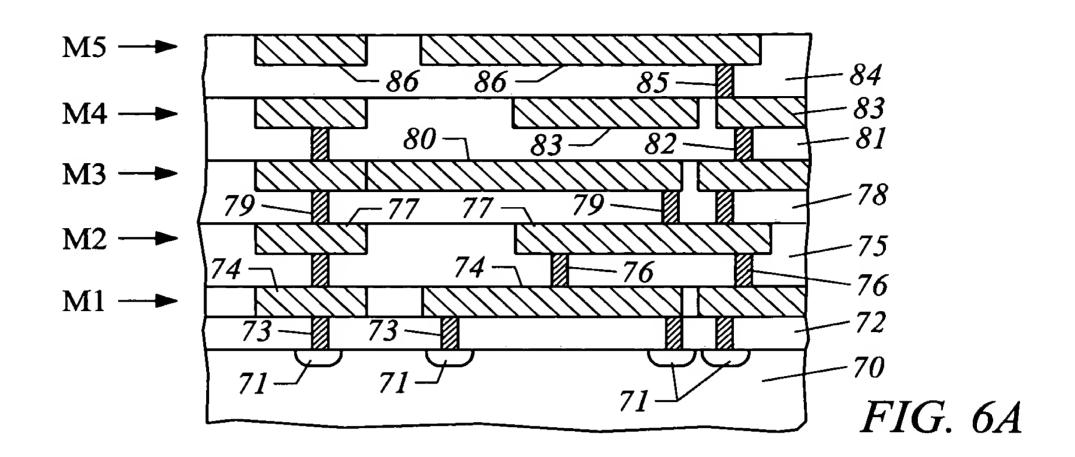
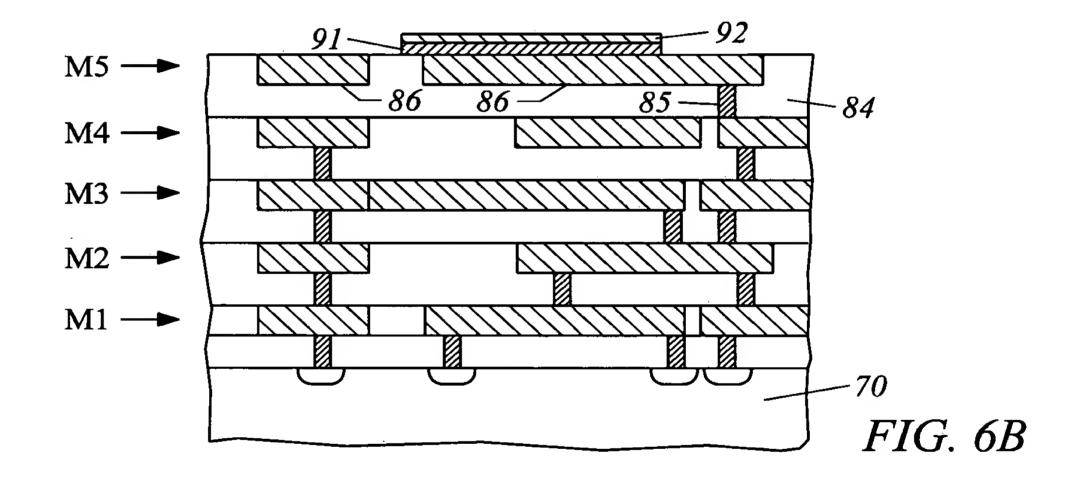


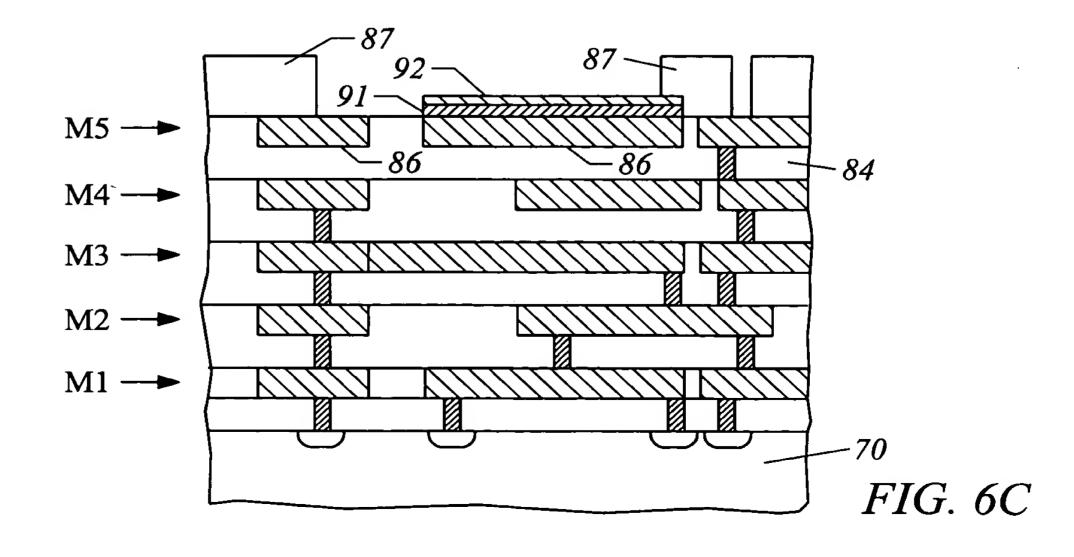
FIG. 5B

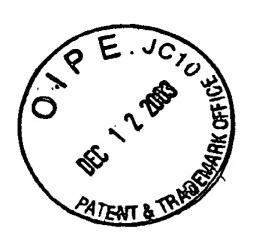


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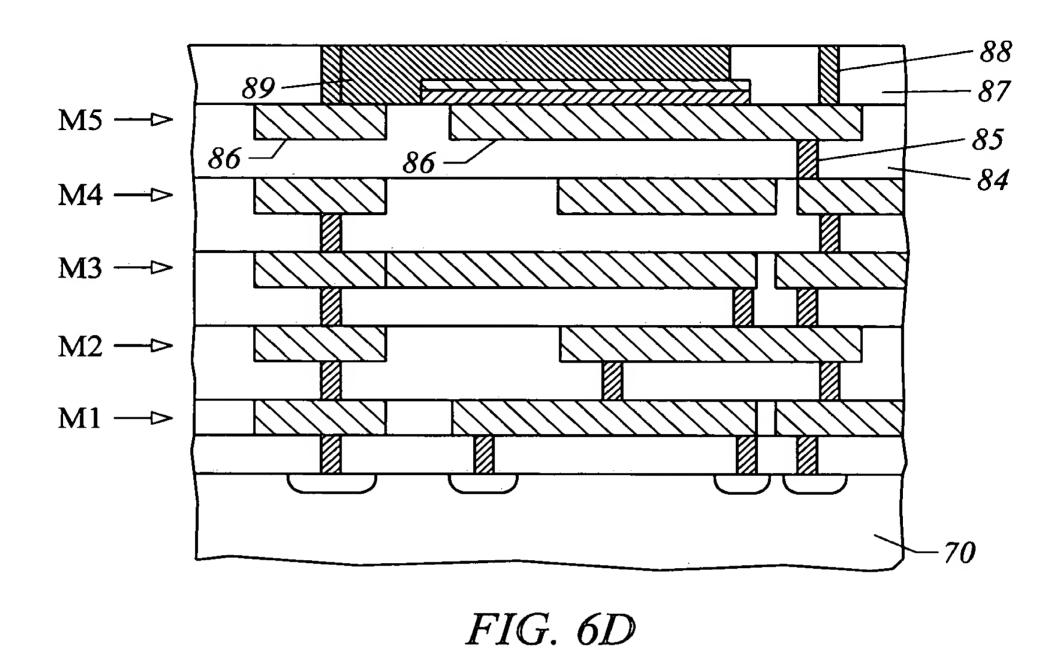








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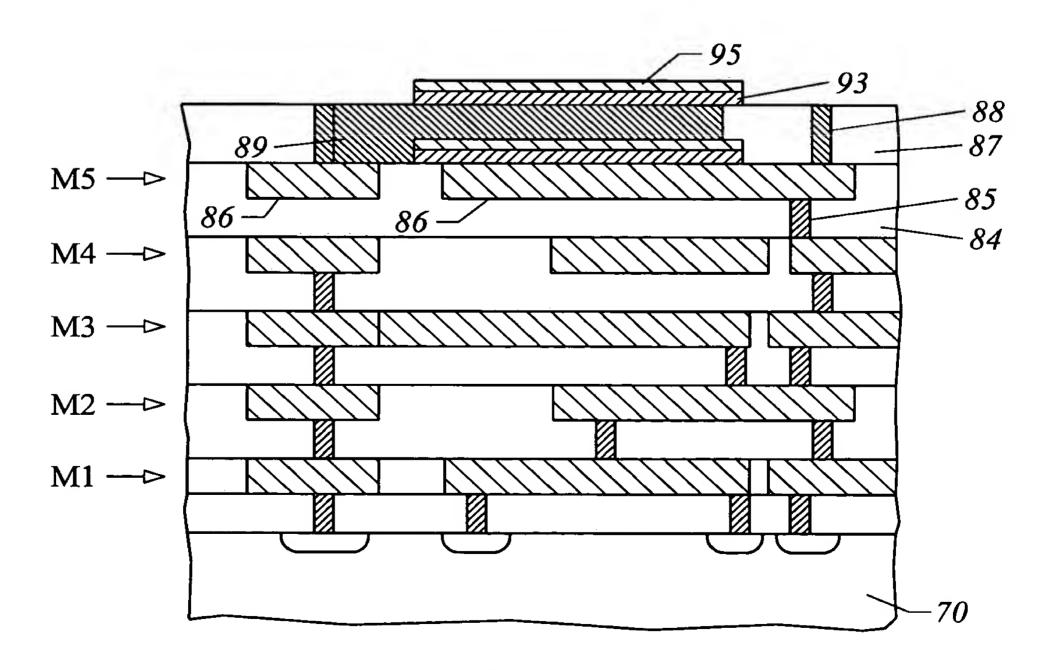
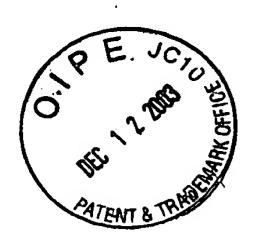
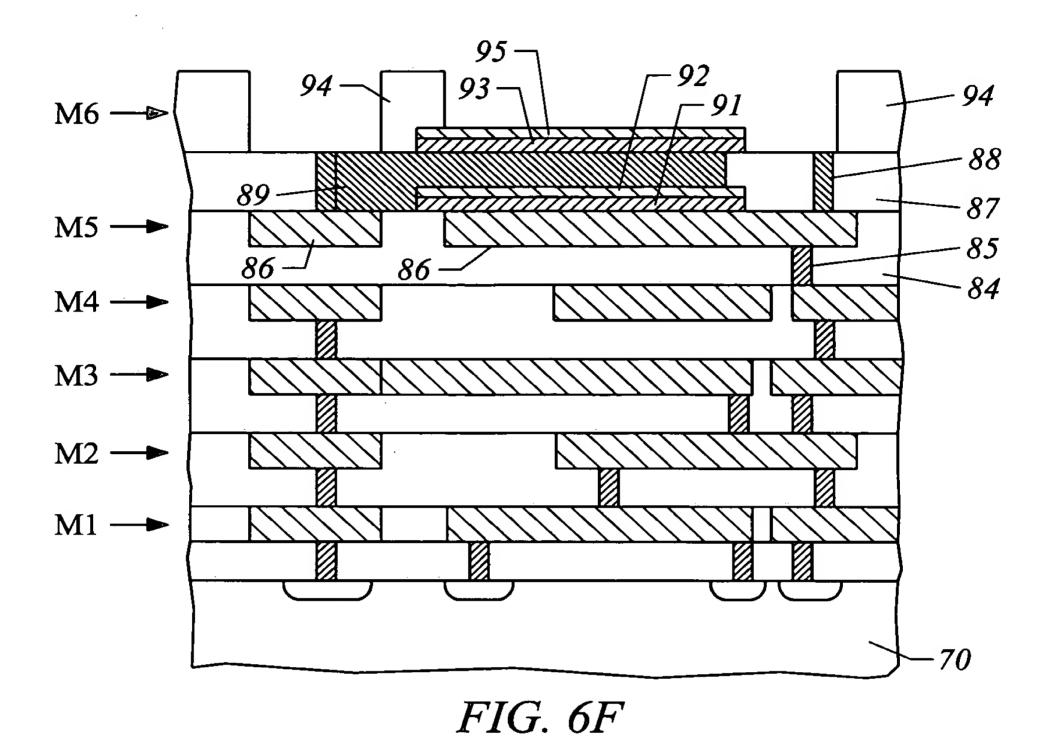


FIG. 6E

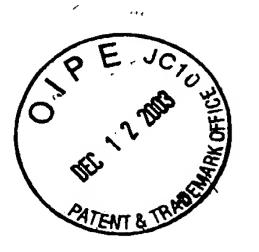


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90-90 93 - 91 M6 88 *89* 87 M5 **→** 86 84 M4 **→** M3 — M2 — M1 _ *-70*

FIG. 6G



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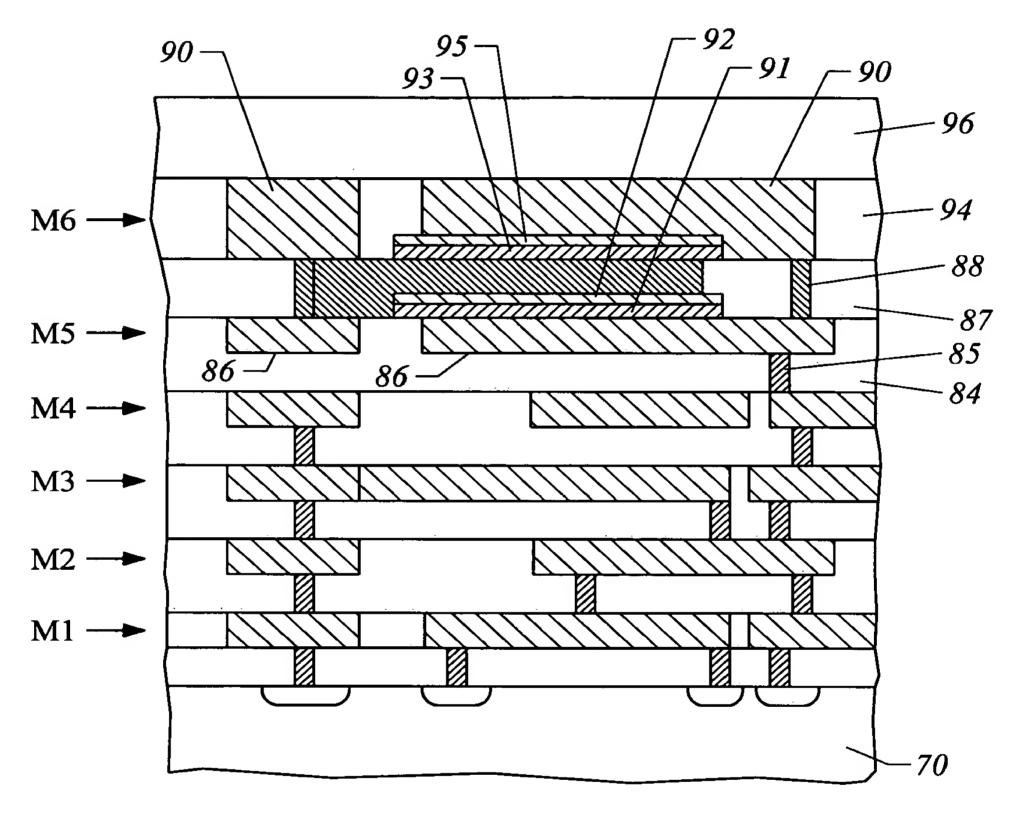


FIG. 6H